

ULTRASONIC ROTARY HEAD BONDER

REBO-9

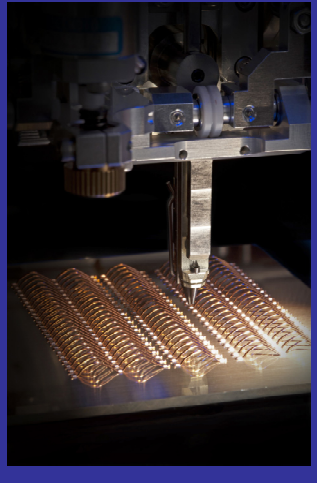


ULTRASONIC ENGINEERING CO., LTD

REBO Series **NEW** model available

REBO-9

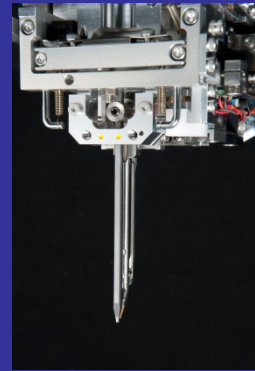
Cu wire bonding
(Φ200~500μm)



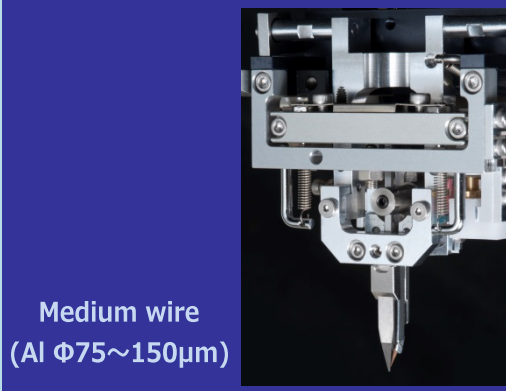
Ribbon bonding
(W:2mm, t:0.2mm)



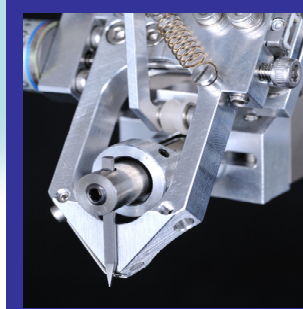
Attach length 66mm
Deep access



Large wire
(Al Φ100~500μm)



Medium wire
(Al Φ75~150μm)



Small wire
(Al Φ25~50μm)

REBO-9 major specification

New digitally controlled generator

- Able to manage 80, 110, 120kHz in 1 generator.
- Conversion to other type became easier.

Lighter rotary part · faster XYZ axis movment.

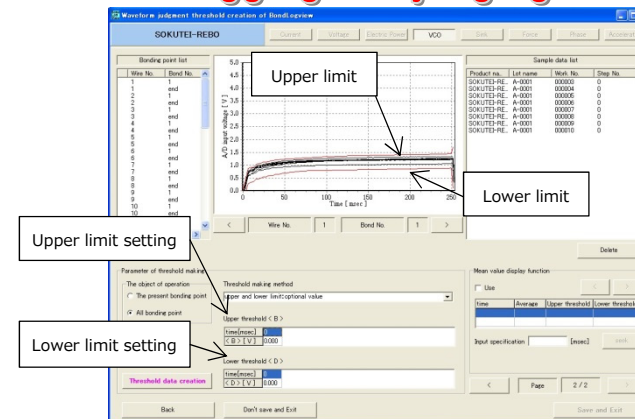
- Bonding head moves 1.33 times faster.
⇒ Bonding tact become approx. 8% faster.

New control system

- Improved workability of maintenance.
- Touch-panel applicable.
- SSD integrated for faster launch.

Current functions are available as well

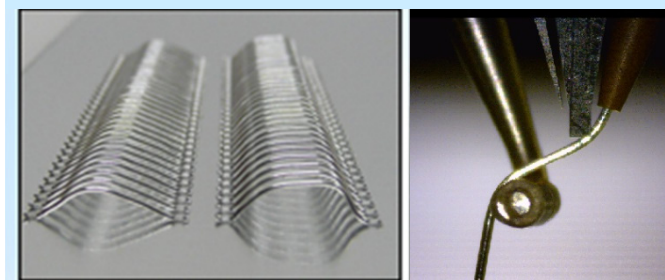
Wave logging and judging function



Loop former

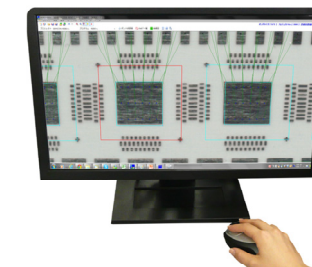
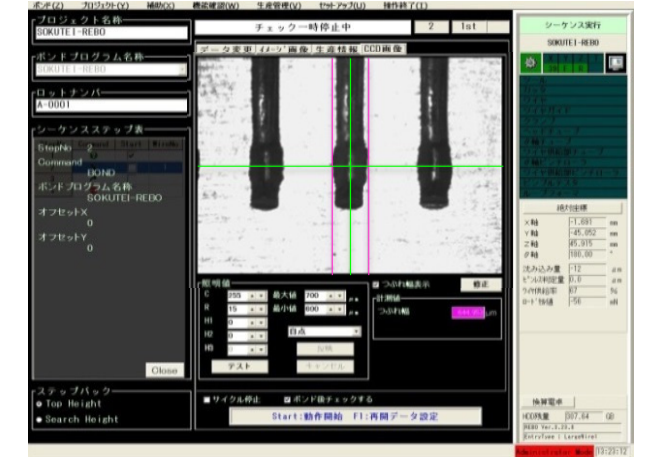
Stable loop form under long span bonding

Loop control



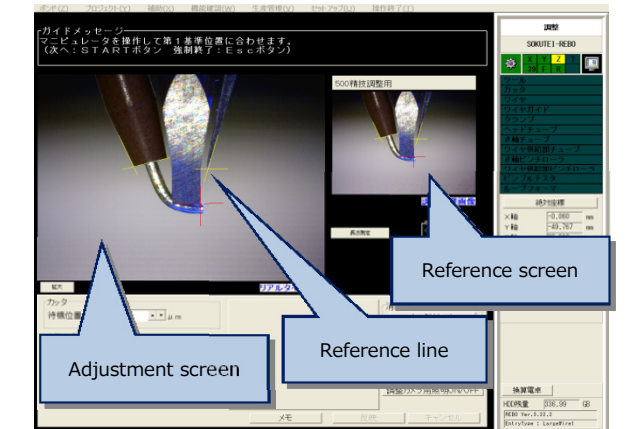
Auto deformation check

- Automatically measure and saves deformation data after bonding.



REBOndWin
Bonding data
making software

Around tool observation
Able to confirm position and adjust
tool, cutter, and wire guide by monitor



High performance wire bonder

MAJOR SPECIFICATION

Item	REBO-9 Series				
Wire	Small wire	Medium wire	Large wire	Ribbon	Cu wire
Wire / Ribbon size	25~50μm	75~150μm	100~500μm	W:0.5mm - 2.0mm t:0.1 - 0.3mm	200~500μm
Wire supply angle	45°	65°	75°	70°	
Wire cut method	Wire clamped Pull cut	Pull cut by XYZ axis movement	Motor driven cutter + XYZ axis movement combined		
Wire material	Aluminum				Copper
Ultrasonic frequency	120kHz	110kHz		80kHz	
Bonding tool	Tools on market	Our original tool			
Bonding method	Ultrasonic wedge bonding				
Bonding area	X:300mm × Y:160mm Standard				
Z-stroke	80mm				
θ-stroke	460°				
Basic OS	Windows 8 [※]				
Around tool observation	Able to manage position of tools and cutters by embedded camera pictures				
Wire program memory	10,000 bonding points / project				
Wave monitor logging	Transducer current & voltage, power, sink depth, phase, and voltage controlled oscillation. *VCO is not available for small wire.				
Pin less pull tester	Not available	Available		Not available	
Data making support	Offline data making software REBOnWin				
Product size	Approx. 710(W)×1225(D)×1630(H)mm (Signal tower and other projectiles not included.)				
Mass weight	Approx. 620kg				
Power source	Single phase 200V±5V 50/60Hz		Approx. 700VA		
Pneumatic source	0.49MPa				
Body color	Munsell N9.0 (Gloss)				

※ Windows is a registered trademark of United States Microsoft Corporation.



Caution: Please read operation manual carefully before using.

※The specification and outer dimensions are subject to change without prior notice for improvement.

<http://www.cho-onpa.co.jp/> Latest information available.

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